

DATASHEET

Description

The 9DBV0441 is a member of IDT's SOC-Friendly 1.8V Very-Low-Power (VLP) PCIe family. It has integrated output terminations providing Zo=100ohms for direct connection to 100ohm transmission lines. The device has 4 output enables for clock management, and 3 selectable SMBus addresses.

Recommended Application

1.8V PCIe Gen1-2-3 Zero-Delay/Fan-out Buffer (ZDB/FOB)

Output Features

4 – 1-200Hz Low-Power (LP) HCSL DIF pairs w/Zo=100Ω

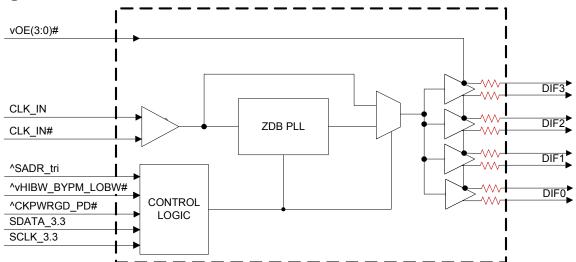
Key Specifications

- DIF cycle-to-cycle jitter <50ps
- DIF output-to-output skew <50ps
- DIF additive phase jitter is <100fs rms for PCIe Gen3
- DIF additive phase jitter <300fs rms for 12kHz-20MHz

Features/Benefits

- Direct connection to 100ohm transmission lines; saves 16 resistors compared to standard HCSL outputs
- 53mW typical power consumption in PLL mode; minimal power consumption
- Spread Spectrum (SS) compatible; allows use of SS for EMI reduction
- OE# pins; support DIF power management
- HCSL compatible differential input; can be driven by common clock sources
- Programmable Slew rate for each output; allows tuning for various line lengths
- Programmable output amplitude; allows tuning for various application environments
- Pin/software selectable PLL bandwidth and PLL Bypass; minimize phase jitter for each application
- Outputs blocked until PLL is locked; clean system start-up
- Software selectable 50MHz or 125MHz PLL operation; useful for Ethernet applications
- Configuration can be accomplished with strapping pins; SMBus interface not required for device control
- 3.3V tolerant SMBus interface works with legacy controllers
- Space saving 32-pin 5x5mm VFQFPN; minimal board space
- Selectable SMBus addresses; multiple devices can easily share an SMBus segment

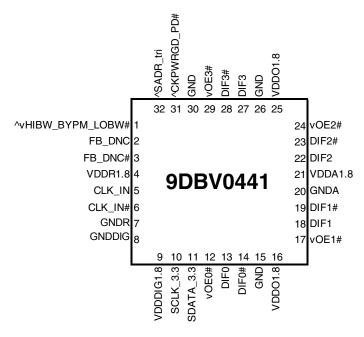
Block Diagram



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Pin Configuration



32-pin VFQFPN, 5x5 mm, 0.5mm pitch

^ prefix indicates internal 120KOhm pull up resistor
^v prefix indicates internal 120KOhm pull up AND pull down resistor (biased to VDD/2)
v prefix indicates internal 120KOhm pull down resistor

SMBus Address Selection Table

	SADR	Address	+ Read/Write bit
State of SADR on first application of CKPWRGD_PD#	0	1101011	Х
	M	1101100	х
	1	1101101	х

Power Management Table

CKPWRGD_PD#	CLK IN	SMBus	OEx# Pin	DIF	DIFx		
	CLK_IN	OEx bit	OLX# FIII	True O/P	Comp. O/P	PLL	
0	Х	Х	Х	Low	Low	Off	
1	Running	0	Х	Low	Low	On ¹	
1	Running	1	0	Running	Running	On ¹	
1	Running	1	1	Low	Low	On ¹	

^{1.} If Bypass mode is selected, the PLL will be off, and outputs will be running.



Power Connections

Pin Numb	Description	
VDD	GND	Description
4	7	Input receiver analog
9	8	Digital Power
16, 25	15,20,26,30	DIF outputs
21	20	PLL Analog

Frequency Select Table

FSEL	CLK_IN	DIFx
Byte3 [4:3]	(MHz)	(MHz)
00 (Default)	100.00	CLK_IN
01	50.00	CLK_IN
10	125.00	CLK_IN
11	Reserved	Reserved

PLL Operating Mode

		Byte1 [7:6]	Byte1 [4:3]
HiBW_BypM_LoBW#	MODE	Readback	Control
0	PLL Lo BW	00	00
M	Bypass	01	01
1	PLL Hi BW	11	11

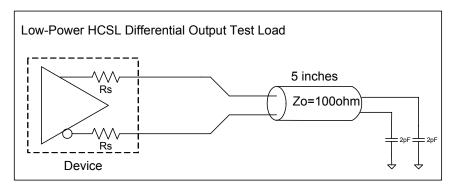


Pin Descriptions

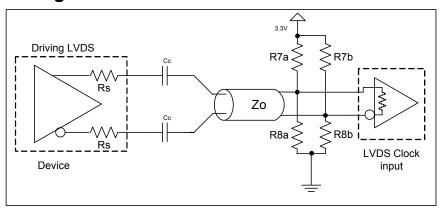
Pin#	Pin Name	Type	Pin Description
1	AVUIDAN DVDM LODAN#	LATCHED IN	Trilevel input to select High BW, Bypass or Low BW mode.
1	^vHIBW_BYPM_LOBW#	LATCHED IN	See PLL Operating Mode Table for Details.
2	FB_DNC	DNC	True clock of differential feedback. The feedback output and feedback input are
	FB_DINC	DNC	connected internally on this pin. Do not connect anything to this pin.
3	FB_DNC#	DNC	Complement clock of differential feedback. The feedback output and feedback
3	I B_DINC#	DIVO	input are connected internally on this pin. Do not connect anything to this pin.
4	VDDR1.8	PWR	1.8V power for differential input clock (receiver). This VDD should be treated as
	_		an Analog power rail and filtered appropriately.
5	CLK_IN	IN	True Input for differential reference clock.
6	CLK_IN#	IN	Complementary Input for differential reference clock.
7	GNDR	GND	Analog Ground pin for the differential input (receiver)
8	GNDDIG	GND	Ground pin for digital circuitry
9	VDDDIG1.8	PWR	1.8V digital power (dirty power)
10	SCLK_3.3	IN	Clock pin of SMBus circuitry, 3.3V tolerant.
11	SDATA_3.3	I/O	Data pin for SMBus circuitry, 3.3V tolerant.
12	vOE0#	IN	Active low input for enabling DIF pair 0. This pin has an internal pull-down.
			1 =disable outputs, 0 = enable outputs
13	DIF0	OUT	Differential true clock output
14	DIF0#	OUT	Differential Complementary clock output
15	GND	GND	Ground pin.
16	VDDO1.8	PWR	Power supply for outputs, nominally 1.8V.
17	vOE1#	IN	Active low input for enabling DIF pair 1. This pin has an internal pull-down.
	5.15.4	0.1.=	1 =disable outputs, 0 = enable outputs
18	DIF1	OUT	Differential true clock output
19	DIF1#	OUT	Differential Complementary clock output
20	GNDA	GND	Ground pin for the PLL core.
21	VDDA1.8	PWR	1.8V power for the PLL core.
22	DIF2	OUT	Differential true clock output
23	DIF2#	OUT	Differential Complementary clock output
24	vOE2#	IN	Active low input for enabling DIF pair 2. This pin has an internal pull-down.
0.5	VDD01.0	PWR	1 =disable outputs, 0 = enable outputs
25	VDDO1.8 GND	GND	Power supply for outputs, nominally 1.8V. Ground pin.
26			
27 28	DIF3 DIF3#	OUT OUT	Differential true clock output
_∠ၓ	DIL9#	001	Differential Complementary clock output Active law input for applying DIF pair 3. This pip has an internal pull down
29	vOE3#	IN	Active low input for enabling DIF pair 3. This pin has an internal pull-down.
30	GND	GND	1 =disable outputs, 0 = enable outputs Ground pin.
30	טווט	GND	Input notifies device to sample latched inputs and start up on first high assertion.
31	VCKBMBCD BD#	IN	Low enters Power Down Mode, subsequent high assertions exit Power Down
اد	^CKPWRGD_PD#	IIN	Mode. This pin has internal pull-up resistor.
			ivioue. This piithas internal puli-up resistor.
32	^SADR_tri	LATCHED IN	Tri-level latch to select SMBus Address. See SMBus Address Selection Table.



Test Loads



Driving LVDS



Driving LVDS inputs

Driving EVD3 inputs							
	,	Value					
	Receiver has Receiver does not						
Component	termination	have termination	Note				
R7a, R7b	10K ohm	140 ohm					
R8a, R8b	5.6K ohm	75 ohm					
Cc	0.1 uF	0.1 uF					
Vcm	1.2 volts	1.2 volts					



Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9DBV0441. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Supply Voltage	VDDx	Applies to all VDD pins	-0.5		2.5	V	1,2
Input Voltage	V_{IN}		-0.5		$V_{DD} + 0.5V$	V	1, 3
Input High Voltage, SMBus	V_{IHSMB}	SMBus clock and data pins			3.6V	V	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-Clock Input Parameters

TA = T_{COM} or T_{IND}. Supply Voltage per VDD of normal operation conditions, See Test Loads for Loading Conditions

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PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage - DIF_IN	V _{IHDIF}	Differential inputs (single-ended measurement)	600	800	1150	mV	1
Input Low Voltage - DIF_IN	V _{ILDIF}	Differential inputs (single-ended measurement)	V _{SS} - 300	0	300	mV	1,3
Input Common Mode Voltage - DIF_IN	V_{COM}	Common Mode Input Voltage	300		725	mV	1
Input Amplitude - DIF_IN	V_{SWING}	Peak to Peak value (V _{IHDIF} - V _{ILDIF})	300		1450	mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4			V/ns	1,2
Input Leakage Current	I _{IN}	$V_{IN} = V_{DD}$, $V_{IN} = GND$	-5		5	uA	1
Input Duty Cycle	d_{tin}	Measurement from differential wavefrom	45		55	%	1
Input Jitter - Cycle to Cycle	J_{DIFIn}	Differential Measurement	0		150	ps	1

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² Operation under these conditions is neither implied nor guaranteed.

³ Not to exceed 2.5V.

² Slew rate measured through +/-75mV window centered around differential zero

³ The device can be driven from a single ended clock by driving the true clock and biasing the complement clock input to the V_{BIAS} , where V_{BIAS} is $(V_{IHHIGH} - V_{IHLOW})/2$



Electrical Characteristics-Input/Supply/Common Parameters-Normal Operating Conditions

 $TA = T_{COM}$ or T_{IND} ; Supply Voltage per VDD of normal operation conditions, See Test Loads for Loading Conditions

, , ,	<u> </u>	or normal operation conditions, occ rest Loads to					
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
1.8V Supply Voltage	VDD	Supply voltage for core, analog and LVCMOS outputs	1.7	1.8	1.9	V	1
Ambient Operating	T _{COM}	Commmercial range	0	25	70	°C	1
Temperature	T_IND	Industrial range	-40	25	85	°C	1
Input High Voltage	V_{IH}	Single-ended inputs, except SMBus	0.75 V _{DD}		$V_{DD} + 0.3$	V	1
Input Mid Voltage	V_{IM}	Single-ended tri-level inputs ('_tri' suffix)	0.4 V _{DD}		0.6 V _{DD}	V	1
Input Low Voltage	V_{IL}	Single-ended inputs, except SMBus	-0.3		0.25 V _{DD}	V	1
	I _{IN}	Single-ended inputs, $V_{IN} = GND$, $V_{IN} = VDD$	-5		5	uA	1
Input Current	I _{INP}	Single-ended inputs $V_{IN} = 0 \text{ V}$; Inputs with internal pull-up resistors $V_{IN} = \text{VDD}$; Inputs with internal pull-down resistors	-200		200	uA	1
	F _{ibyp}	Bypass mode	1		200	MHz	2
Innut Fraguency	F _{ipll100}	100MHz PLL mode	50	100.00	140	MHz	2
Input Frequency	F _{ipll125}	125MHz PLL mode	62.5	125.00	175	MHz	2
	F _{ipll62}	50MHz PLL mode	25	50.00	65	MHz	2
Pin Inductance	L _{pin}				7	nΗ	1
	C _{IN}	Logic Inputs, except DIF_IN	1.5		5	pF	1
Capacitance	C _{INDIF_IN}	DIF_IN differential clock inputs	1.5		2.7	pF	1,6
	C _{OUT}	Output pin capacitance			6	pF	1
Clk Stabilization	T _{STAB}	From V _{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock		0.6	1	ms	1,2
Input SS Modulation Frequency	f _{MODIN}	Allowable Frequency (Triangular Modulation)	30	31.500	33	kHz	1
OE# Latency	t _{LATOE#}	DIF start after OE# assertion DIF stop after OE# deassertion	1		3	clocks	1,3
Tdrive_PD#	t _{DRVPD}	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	t _F	Fall time of single-ended control inputs			5	ns	1,2
Trise	t _R	Rise time of single-ended control inputs			5	ns	1,2
SMBus Input Low Voltage	V_{ILSMB}	$V_{DDSMB} = 3.3V$, see note 4 for $V_{DDSMB} < 3.3V$			0.8	V	1, 4
SMBus Input High Voltage	V_{IHSMB}	$V_{DDSMB} = 3.3V$, see note 5 for $V_{DDSMB} < 3.3V$	2.1		3.6	V	1, 5
SMBus Output Low Voltage	V_{OLSMB}	@ I _{PULLUP}			0.4	V	1
SMBus Sink Current	I _{PULLUP}	@ V _{OL}	4			mA	1
Nominal Bus Voltage	V_{DDSMB}		1.7		3.6	V	1
SCLK/SDATA Rise Time	t _{RSMB}	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t _{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f _{MAXSMB}	Maximum SMBus operating frequency			400	kHz	1,7

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 $^{^2\}mbox{Control}$ input must be monotonic from 20% to 80% of input swing.

³Time from deassertion until outputs are >200 mV

 $^{^4}$ For $V_{DDSMB} < 3.3V$, $V_{ILSMB} <= 0.35V_{DDSMB}$

 $^{^{5}}$ For $V_{DDSMB} < 3.3V$, $V_{IHSMB} >= 0.65V_{DDSMB}$

⁶DIF_IN input

⁷The differential input clock must be running for the SMBus to be active



Electrical Characteristics-DIF 0.7V Low Power HCSL Outputs

TA = T_{COM} or T_{IND}: Supply Voltage per VDD of normal operation conditions, See Test Loads for Loading Conditions

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PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	Trf	Scope averaging on 3.0V/ns setting	1.1	2	3	V/ns	1, 2, 3
Siew rate	111	Scope averaging on 2.0V/ns setting	1.9	3	4	V/ns	1, 2, 3
Slew rate matching	∆Trf	Slew rate matching, Scope averaging on		7	20	%	1, 2, 4
Voltage High	V _{HIGH}	Statistical measurement on single-ended signal using oscilloscope math function. (Scope	660	774	850	mV	1,7
Voltage Low	V_{LOW}	averaging on)		18	150	""	1,7
Max Voltage	Vmax	Measurement on single ended signal using		821	1150	mV	1
Min Voltage	Vmin	absolute value. (Scope averaging off)	-300	-15		TIIIV	1
Vswing	Vswing	Scope averaging off	300	1536		mV	1,2,7
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	250	414	550	mV	1,5,7
Crossing Voltage (var)	Δ-Vcross	Scope averaging off		13	140	mV	1, 6

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-Current Consumption

 $TA = T_{COM}$ or T_{IND} ; Supply Voltage per VDD of normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I _{DDAOP}	VDDA+VDDR, PLL Mode, @100MHz		11	15	mA	1
	I _{DDOP}	VDD1.8, All outputs active @100MHz		25	35	mA	1
Powerdown Current	I _{DDAPD}	VDDA+VDDR, PLL Mode, @100MHz			1	mA	1,2
	I _{DDPD}	VDD1.8, Outputs Low/Low			1.2	mA	1, 2

¹ Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all Vcross measurements in any particular system. Note that this is a subset of Vcross_min/max (Vcross absolute) allowed. The intent is to limit Vcross induced modulation by setting Δ-Vcross to be smaller than Vcross absolute.

⁷ At default SMBus settings.

² Input clock stopped.



Electrical Characteristics-Output Duty Cycle, Jitter, Skew and PLL Characteristics

TA = T_{COM} or T_{IND}; Supply Voltage per VDD of normal operation conditions, See Test Loads for Loading Conditions

17.4 - Toom of Tind; Supply Voltage per VEB of Normal operation conditions, See Took Education Conditions							
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
PLL Bandwidth	BW	-3dB point in High BW Mode	2	2.7	4	MHz	1,5
FLL Balluwidili	DVV	-3dB point in Low BW Mode	-3dB point in High BW Mode 2 2.7 4 MHz -3dB point in Low BW Mode 1 1.4 2 MHz Peak Pass band Gain 1.2 2 dB asured differentially, PLL Mode 45 50.1 55 % differentially, Bypass Mode @100MHz -1 0 1 % Bypass Mode, V _T = 50% 3000 3600 4500 ps PLL Mode V _T = 50% 0 92 200 ps V _T = 50% 28 50 ps PLL mode 16 50 ps	1,5			
PLL Jitter Peaking	t _{JPEAK}	Peak Pass band Gain	1.2 2 dB 45 50.1 55 %		1		
Duty Cycle	t _{DC}	Measured differentially, PLL Mode	45	50.1	55	%	1
Duty Cycle Distortion	t _{DCD}	Measured differentially, Bypass Mode @100MHz	-1	0	1	%	1,3
Ckow Input to Output	t _{pdBYP}	Bypass Mode, V _T = 50%	3000	3600	4500	1 %	
Skew, Input to Output	t _{pdPLL}	PLL Mode V _T = 50%	0	92	200	4 MHz 2 MHz 2 dB 55 % 1 % 600 ps 600 ps 600 ps 600 ps 600 ps	1,4
Skew, Output to Output	t _{sk3}	V _T = 50%		28	50	ps	1,4
Jitter, Cycle to cycle	+	PLL mode		16	50	ps	1,2
Jitter, Cycle to cycle	t _{jcyc-cyc}	Additive Jitter in Bypass Mode		0.1	25	ps	1,2

¹ Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-Phase Jitter Parameters

TA = T_{COM} or T_{IND;} Supply Voltage per VDD of normal operation conditions, See Test Loads for Loading Conditions

			PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz PCIe Gen 2 High Band .5MHz < f < Nyquist (50MHz) PCIe Gen 3 BW of 2-4MHz, CDR = 10MHz) PCIe Gen 1 PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz 10kHz < f < 1.5MHz 10kHz < f < 0.5 PCIe Gen 1 PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz 10kHz < f < 1.5MHz 10kHz < f < 1.5MHz PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz PCIe Gen 3 BW of 2-4MHz PCIe Gen 3 BW of 2-4MHz PCIE Gen 3 BW of 2-4M					
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	LIMIT	UNITS	Notes
PARAMETER SYMBOL CONDITIONS MIN TYP MAX LIMIT UNIT UNIT LightPoleG1 PCle Gen 1 34 52 86 ps (p PCle Gen 2 Lo Band 10kHz < f < 1.5MHz < f < 1.5MHz PCle Gen 2 Lo Band 10kHz < f < 1.5MHz PCle Gen 2 Lo Band 10kHz < f < 1.5MHz < f < Nyquist (50MHz) PCle Gen 3 PCle Gen 4 PCle Gen 5 PCle	ps (p-p)	1,2,3						
				0.9	1.4	3		1,2
		2.2	2.5	3.1		1,2		
	t _{jphPCleG3}			0.5	0.6	1		1,2,4
	t _{jphSGMII}			1.9	2	NA		1,6
	t _{jphPCleG1}	PCIe Gen 1		0.6	5	N/A	ps (p-p)	1,2,3
				0.1	0.3	N/A		1,2,5
	t _{jph} PCleG2	j s		0.05	0.1	N/A		1,2,5
	t _{jphPCleG3}			0.05	0.1	N/A		1,2,4, 5
,,	t _{jphSGMIIMO}			165	200	N/A		1,6
	t _{jphSGMIIM1}	·		251	300	N/A	_	1,6

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

⁴ All outputs at default slew rate

⁵ The MIN/TYP/MAX values of each BW setting track each other, i.e., Low BW MAX will never occur with Hi BW MIN.

² See http://www.pcisig.com for complete specs

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

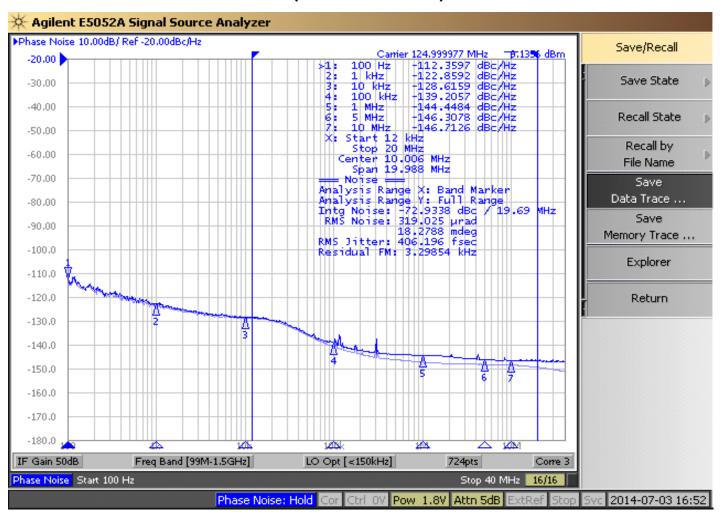
 $^{^4}$ For RMS figures, additive jitter is calculated by solving the following equation: Additive jitter = SQRT[(total jitter)^2 - (input jitter)^2]

⁵ Driven by 9FGV0831 or equivalent

⁶ Driven by Rohde&Schwarz SMA100



Additive Phase Jitter Plot: 125M (12kHz to 20MHz)





General SMBus Serial Interface Information

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) sends the byte count = X
- IDT clock will acknowledge
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will acknowledge each byte one at a time
- Controller (host) sends a Stop bit

	Index Blo	ck \	Write Operation
Controll	er (Host)		IDT (Slave/Receiver)
Т	starT bit		
Slave A	Address		
WR	WRite		
			ACK
Beginning	Byte = N		
			ACK
Data Byte	Count = X		
			ACK
Beginnin	g Byte N	×	
		X Byte	ACK
0			
0			0
0			0
			0
Byte N	+ X - 1		
			ACK
Р	stoP bit		

Note: SMBus Address is Latched on SADR pin.

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- · Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will acknowledge
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends Byte 0 through Byte X (if X_(H) was written to Byte 8)
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

	Index Block Read Operation					
Co	ntroller (Host)		IDT (Slave/Receiver)			
Т	starT bit					
S	lave Address					
WR	WRite					
			ACK			
Beg	inning Byte = N					
			ACK			
RT	Repeat starT					
S	lave Address					
RD	ReaD					
			ACK			
			Data Byte Count=X			
	ACK					
			Beginning Byte N			
	ACK					
			0			
	0		0			
	0	40	0			
	0					
		X Byte	Byte N + X - 1			
N	Not acknowledge					
Р	stoP bit					



SMBus Table: Output Enable Register ¹

Byte 0	Name	Control Function	Туре	0	1	Default	
Bit 7	Reserved						
Bit 6	DIF OE3	Output Enable	RW	Low/Low	Enabled	1	
Bit 5	DIF OE2	Output Enable	RW	Low/Low	Enabled	1	
Bit 4	Reserved						
Bit 3	DIF OE1	Output Enable	RW	Low/Low	Enabled	1	
Bit 2		Reserved				1	
Bit 1	DIF OE0	Output Enable RW Lo		Low/Low	Enabled	1	
Bit 0		Reserved				1	

^{1.} A low on these bits will overide the OE# pin and force the differential output Low/Low

SMBus Table: PLL Operating Mode and Output Amplitude Control Register

Byte 1	Name	Control Function	Туре	0	1	Default
Bit 7	PLLMODERB1	PLL Mode Readback Bit 1	R	See PLL Operating Mode Table		Latch
Bit 6	PLLMODERB0	PLL Mode Readback Bit 0	R			Latch
Bit 5	PLLMODE SWCNTRL	Enable SW control of PLL Mode	RW	Values in B1[7:6]	Values in B1[4:3]	0
ысэ	T ELMODE_OVIGITIE	Enable 644 control of 1 EE Wode	1200	set PLL Mode	set PLL Mode	U
Bit 4	PLLMODE1	PLL Mode Control Bit 1	RW ¹	See PLL Operating Mode Table		0
Bit 3	PLLMODE0	PLL Mode Control Bit 0	RW ¹	See FLL Opera	ing wode rable	0
Bit 2		Reserved				1
Bit 1	AMPLITUDE 1	Controls Output Amplitude	RW	00 = 0.6V	01 = 0.7V	1
Bit 0	AMPLITUDE 0	Controls Catput Amplitude	RW	10= 0.8V	11 = 0.9V	0

^{1.} B1[5] must be set to a 1 for these bits to have any effect on the part.

SMBus Table: DIF Slew Rate Control Register

Byte 2	Name	Control Function	Туре	0	1	Default
Bit 7	Reserved					
Bit 6	SLEWRATESEL DIF3	Slew Rate Selection	RW	2 V/ns	3 V/ns	1
Bit 5	SLEWRATESEL DIF2	Slew Rate Selection	RW	2 V/ns	3 V/ns	1
Bit 4	Reserved					
Bit 3	SLEWRATESEL DIF1	Slew Rate Selection	RW	2 V/ns	3 V/ns	1
Bit 2		Reserved				1
Bit 1	SLEWRATESEL DIF0	Slew Rate Selection	Slew Rate Selection RW 2 V/ns		3 V/ns	1
Bit 0		Reserved				1

SMBus Table: Frequency Select Control Register

Byte 3	Name	Control Function	Туре	0	1	Default	
Bit 7		Reserved					
Bit 6		Reserved					
Bit 5	FREQ_SEL_EN	Enable SW selection of frequency	RW	SW frequency SW frequency change disabled change enabled		0	
Bit 4	FSEL1	Freq. Select Bit 1	RW ¹	See Frequency	0		
Bit 3	FSEL0	Freq. Select Bit 0	RW ¹	occ i requeries	y ocicet rabic	0	
Bit 2	Reserved					1	
Bit 1	Reserved				1		
Bit 0	SLEWRATESEL FB	Adjust Slew Rate of FB	RW	2V/ns	3V/ns	1	

^{1.} B3[5] must be set to a 1 for these bits to have any effect on the part.

Byte 4 is Reserved and reads back 'hFF



SMBus Table: Revision and Vendor ID Register

Byte 5	Name	Control Function	Туре	0	1	Default
Bit 7	RID3		R			0
Bit 6	RID2	Revision ID	R	A rev =	0	
Bit 5	RID1	TO THE MISION ID	R	7 16V -	0	
Bit 4	RID0		R		0	
Bit 3	VID3		R			0
Bit 2	VID2	VENDOR ID	R	0001	- IDT	0
Bit 1	VID1	VENDOR ID	R	0001 = IDT		0
Bit 0	VID0		R			1

SMBus Table: Device Type/Device ID

Byte 6	Name	Control Function	Туре	0	1	Default	
Bit 7	Device Type1	Device Type	R	00 = FGV,	01 = DBV,	0	
Bit 6	Device Type0	Device Type	R	10 = DMV, 1	1		
Bit 5	Device ID5		R			0	
Bit 4	Device ID4		R				
Bit 3	Device ID3	Device ID	R	000100 hina	ny or 04 hey	0	
Bit 2	Device ID2	Device iD	R	000100 billa	1100 binary or 04 hex		
Bit 1	Device ID1		R			0	
Bit 0	Device ID0		R			0	

SMBus Table: Byte Count Register

Byte 7	Name	Control Function	Type	0	1	Default
Bit 7		Reserved				0
Bit 6		Reserved				0
Bit 5		Reserved				0
Bit 4	BC4		RW			0
Bit 3	BC3		RW	Writing to this regist	er will configure how	1
Bit 2	BC2	Byte Count Programming	RW	many bytes will be r	ead back, default is	0
Bit 1	BC1		RW	= 8 b	ytes.	0
Bit 0	BC0		RW			0



Marking Diagrams

ICS
BV0441AL
YYWW
COO
LOT



Notes:

- 1. "LOT" is the lot sequence number.
- 2. "COO" denotes country of origin.
- 3. YYWW is the last two digits of the year and week that the part was assembled.
- 4. Line 2: truncated part number
- 5. "L" denotes RoHS compliant package.
- 6. "I" denotes industrial temperature range device.

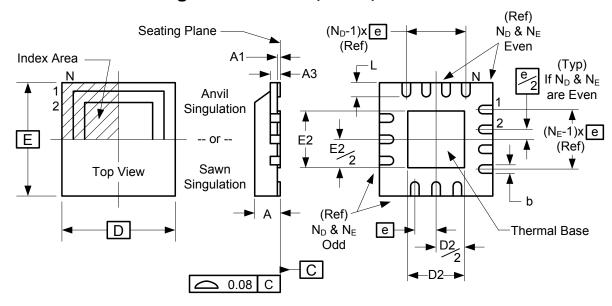
Thermal Characteristics

PARAMETER	SYMBOL	CONDITIONS	PKG	TYP VALUE	UNITS	NOTES
	θ_{JC}	Junction to Case		42	°C/W	1
	θ_{Jb}	Junction to Base		2.4	°C/W	1
Thermal Resistance	θ_{JA0}	Junction to Air, still air	NLG32 39		°C/W	1
Theimai nesistance	θ_{JA1}	Junction to Air, 1 m/s air flow	INLUSZ	33	°C/W	1
	θ_{JA3}	Junction to Air, 3 m/s air flow		28	°C/W	1
	θ_{JA5}	Junction to Air, 5 m/s air flow		27	°C/W	1

¹ePad soldered to board



Package Outline and Package Dimensions (NLG32)



	Millimeters		
Symbol	Min	Max	
Α	0.80	1.00	
A1	0	0.05	
A3	0.20 Reference		
b	0.18	0.3	
е	0.50 BASIC		
D x E BASIC	5.00 x 5.00		
D2 MIN./MAX.	3.00	3.30	
E2 MIN./MAX.	3.00	3.30	
L MIN./MAX.	0.30	0.50	
N	32		
N_D	8		
N _E	8		

Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
9DBV0441AKLF	Trays	32-pin VFQFPN	0 to +70° C
9DBV0441AKLFT	Tape and Reel	32-pin VFQFPN	0 to +70° C
9DBV0441AKILF	Trays	32-pin VFQFPN	-40 to +85° C
9DBV0441AKILFT	Tape and Reel	32-pin VFQFPN	-40 to +85° C

[&]quot;LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

[&]quot;A" is the device revision designator (will not correlate with the datasheet revision).



Revision History

		1		
Rev.	Initiator	Issue Date	Description	Page #
А	RDW	8/13/2012	 Removed "Differential" from DS title and Recommended Application, corrected typo's in Description. Updated block diagram to indicate internal terminations. Corrected spelling error in pullup/pulldown text under pinout Updated all electrical tables and added "Industry Limit" column to "Phase Jitter Parameters". Updated Byte3[0] to be consistent with Byte 2. Updated Byte6[7:6] definition. Added thermal data to page 12. Added NLG32 to "Package Outline and Package Dimensions" on page 13. Move to final. 	1,2,5- 8,10, 12,13
В	RDW	2/25/2013	Changed VIH min. from 0.65*VDD to 0.75*VDD Changed VIL max. from 0.35*VDD to 0.25*VDD Added missing mid-level input voltage spec (VIM) of 0.4*VDD to 0.6*VDD.	6
С	RDW	10/27/2014	Updated front page text for consistency and updated block diagram resistor colors to highlight internal resistors. Updated max frequency of 100MHz PLL mode from 110MHz to 140MHz Updated max frequency of 125MHz PLL mode from 137.5MHz to 175MHz Updated max frequency of 50MHz PLL mode from 55MHz to 65MHz	1,6
D	RDW	11/26/2014	Updated Key Specifications with addtive phase jitter. Added additive phase jitter plot to specifications.	1, 9-10
Е	RDW	4/22/2016	Updated max frequency of 100MHz PLL mode to 140MHz Updated max frequency of 125MHz PLL mode to 175MHz Updated max frequency of 50MHz PLL mode to 65MHz	7



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